

Self-leveling, withstands high humidity environments

5108 is a black, electrically isolating epoxy adhesive specifically designed for potting and sealing electronic components. 5108 is a self-leveling material that exhibits low shrinkage once cured and can withstand high temperatures and high humidity or wet environments. This material is also environmentally friendly and considered non-hazardous per D.O.T. regulations. 5108 is available in one-part pre-mixed and frozen syringes and two-part room temperature stable kits.

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|------------------------------|--|
| UNCURED | |
| Pot Life @ 25°C | 2 hours |
| Viscosity, Part A @25°C | 2,100 cPs |
| Viscosity, Part B @25°C | 11,000 cPs |
| Viscosity, mixed @ 25°C | 5,000 cPs |
| Shelf Life, PMF | @ -40°C 6 Months |
| Shelf Life, 2-Part Kit | @18°C to 25°C 12 Months |
| Mix Ratio | 100A to 51.75B parts by weight |
| CURE OPTIONS | 1 hour @ 92°C 4 hours @ 65°C 48 hours @ 25°C |
| CURED PROPERTIES | Based on cure of 4 hours @ 65°C |
| Color | Black |
| Shore D Hardness | 80 |
| Lap Shear (psi) | 3500 |
| Density (g/cc) | 1.07 |
| Glass Transition Temp (°C) | 45 |
| Shrinkage Linear (%) | 0.26 |
| ELECTRICAL PROPERTIES | Based on cure of 4 hours @ 65°C |
| Dielectric Constant | 3.2 @ 1 kHz |
| Dissipation Factor | 0.008 @ 1 kHz |
| Volume Resistivity (ohm-cm) | 7.0E 13 @ 500 VDC |
| THERMAL PROPERTIES | Based on cure of 4 hours @ 65°C |
| Glass Transition Temp (°C) | 45 |
| Degradation Temp. (°C) | 275 |
| OUTGASSING PROPERTIES | Based on cure of 4 hours @ 65°C |
| TML (%) | 0.75 |
| CVCM (%) | 0.01 |
| WVR (%) | 0.39 |

KEY FEATURES

Adheres to Dissimilar Materials

Self Leveling

Hydrolytic Stability

High Temperature Resistant

Low Shrinkage

Non-hazardous per D.O.T. Regulations

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